

b) contacting the tip of an ultrasonic resonator with an exposed opposite side of a bonding portion of said metal wirings of at least one flexible wiring board piece of two flexible wiring board pieces to be bonded; and

c) applying an ultrasonic wave to said ultrasonic resonator to bond said two metal wirings to be bonded.

3. (Twice Amended) The process according to claim 2, further comprising the steps of:

providing a thermoplastic resin layer on said at least one flexible wiring board piece to be exposed to the bonding portion of said metal wiring before performing step a), and

adhering said two flexible wiring board pieces using said thermoplastic resin layer after performing step c),

wherein said two metal wirings are electrically bonded by the step c).

10. (Twice Amended) A multilayer flexible wiring board that is formed by laminating at least two flexible wiring board pieces having a base film and a metal wiring provided on said base film, wherein at least one flexible wiring board piece has a cover film including a resin film on said metal wiring and a first opening is provided on said cover film, and said metal wiring exists at the bottom of said first opening so that said metal wirings of said flexible wiring board pieces are electrically bonded to each other by applying ultrasonic wave while the part of said metal wiring located at the bottom of said first opening is in close contact with said metal wiring of the other flexible wiring board piece, and further wherein said first opening and said metal wiring located at the bottom of said first opening form a concave, and the part of said metal wiring of the other flexible wiring board piece to be bonded to said concave forms a convex on said base film.

12. (Amended) A multilayer flexible wiring board formed by laminating at least two flexible wiring board pieces having a base film and a metal wiring provided on said base film, wherein said base film of at least one flexible wiring board piece has a second opening in which said metal wiring exists at the bottom so that said metal wirings are electrically bonded to each other by applying ultrasonic wave while said metal wiring of the other flexible wiring board piece is in close contact with said metal wiring located at the bottom of said second opening, said second opening and said metal wiring located at the bottom of the second opening form a concave, and the part of the metal wiring of the other wiring board piece to be bonded to said concave forms a convex.

Please add new claim 22 as follows:

--22. A process for manufacturing a multilayer flexible wiring board according to claim 2 further comprising the steps of:

projecting said bonding portion of one flexible wiring board piece in said two flexible wiring board pieces at the top of a convex and exposing said bonding portion of the other flexible wiring board piece at the bottom of a concave before performing step a), and with said bonding portions being in close contact with each other, putting said bonding portion of the convex into said bonding portion of the concave at step b).--

REMARKS

Claims 2-4, 6, 10-13 and 17-22 are pending in this application. By this Amendment, claim 16 is cancelled, claims 2, 3, 10 and 12 are amended and claim 22 is added. Reconsideration in view of the foregoing amendments and following remarks is respectfully respected.

The attached Appendix includes marked-up copies of each rewritten claim (37 C.F.R. §1.121(c)(1)(ii)).